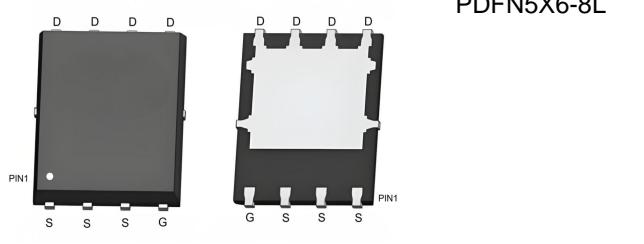


## N-Channel 60V(D-S) MOSFET

Product summary		
V <sub>DS</sub>	60	V
R <sub>DS(ON)</sub> (at V <sub>GS</sub> =10V) Typ.	2.1	mΩ
I <sub>D</sub> (T <sub>c</sub> =25°C)	95	A

Features
<ul style="list-style-type: none"> <li>High density cell design for low R<sub>DS(ON)</sub></li> <li>Split Gate Trench MOSFET technology</li> </ul>
Applications
<ul style="list-style-type: none"> <li>DC-DC Converters</li> <li>Power management functions</li> </ul>

### Pin Configuration



### Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECAP95G06A	PDFN5X6-8L	13"	5000pcs

### Absolute Maximum Ratings (at T<sub>A</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	Rating	Units	
V <sub>DS</sub>	Drain-Source Voltage	60	V	
V <sub>GS</sub>	Gate-Source Voltage	±20	V	
I <sub>D</sub>	Continuous Drain Current <sup>A</sup>	T <sub>C</sub> =25°C	95	A
		T <sub>C</sub> =100°C	60	A
I <sub>DM</sub>	Pulse Drain Current Tested <sup>B</sup>	390	A	
E <sub>AS</sub>	Single Pulse Avalanche Energy <sup>C</sup>	500	mJ	
P <sub>D</sub>	Power Dissipation <sup>D</sup>	120	W	
T <sub>J</sub> , T <sub>STG</sub>	Junction and Storage Temperature Range	-55 to +175	°C	

### Thermal Characteristics

Symbol	Parameter	Typical	Units
R <sub>θJA</sub>	Thermal Resistance-Junction to ambient <sup>E</sup>	20	°C/W
R <sub>θJC</sub>	Thermal Resistance-Junction to case max	1.04	°C/W

Electrical Characteristics (at  $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$	--	--	$\pm 100$	nA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.8	2.2	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	--	2.1	2.5	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=15\text{A}$	--	2.7	3.4	$\text{m}\Omega$
$V_{\text{SD}}$	Diode Forward Voltage	$I_{\text{S}}=20\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1.2	V
$I_{\text{S}}$	Maximum Body-Diode Continuous Current		--	--	95	A
Dynamic Parameters F						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}$ $f=100\text{KHZ}$	--	5950	--	pF
$C_{\text{oss}}$	Output Capacitance		--	1250	--	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	85	--	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=50\text{V}, I_{\text{D}}=50\text{A}$ $V_{\text{GS}}=10\text{V}$	--	93	--	nC
$Q_{\text{gs}}$	Gate-Source Charge		--	17	--	nC
$Q_{\text{gd}}$	Gate-Drain Charge		--	14	--	nC
$t_{\text{D}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=30\text{V}$ $I_{\text{D}}=25\text{A}, R_{\text{G}}=2\Omega,$ $V_{\text{GS}}=10\text{V}$	--	22.5	--	ns
$t_r$	Turn-on Rise Time		--	6.7	--	ns
$t_{\text{D}(\text{off})}$	Turn-off Delay Time		--	80.3	--	ns
$t_f$	Turn-off Fall Time		--	26.9	--	ns
$t_{\text{rr}}$	Reverse recovery time	$I_{\text{F}}=25\text{A},$ $di/dt=100 \text{ A/uS}$	--	68	--	ns
$Q_{\text{rr}}$	Reverse recovery charge		--	73	--	nC

A. The maximum current rating is package limited.

B. Repetitive rating; pulse width limited by max. junction temperature.

C.  $V_{\text{DD}}=50\text{V}$ ,  $R_{\text{G}}=25\Omega$ ,  $L=0.5\text{mH}$ , starting  $T_J=25^\circ\text{C}$ .

D.  $P_D$  is based on max. junction temperature, using junction-case thermal resistance.

E. The value of  $R_{\text{eJA}}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25^\circ\text{C}$ .

F. Guaranteed by design, not subject to production testing.

## Typical Characteristics

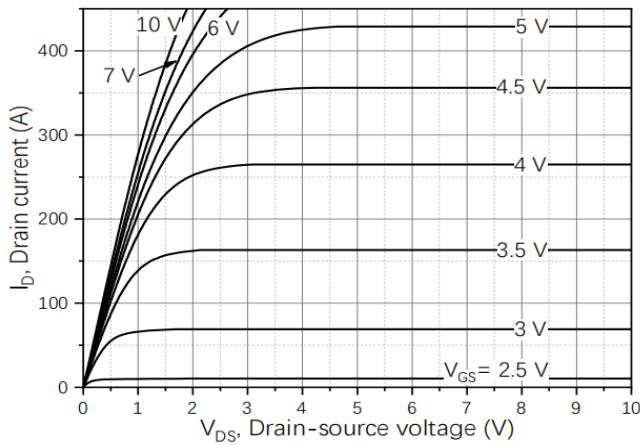


Figure1. Output Characteristics

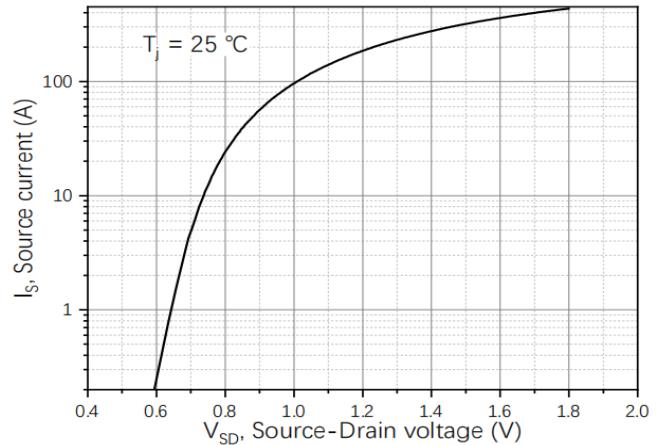


Figure2. Transfer Characteristics

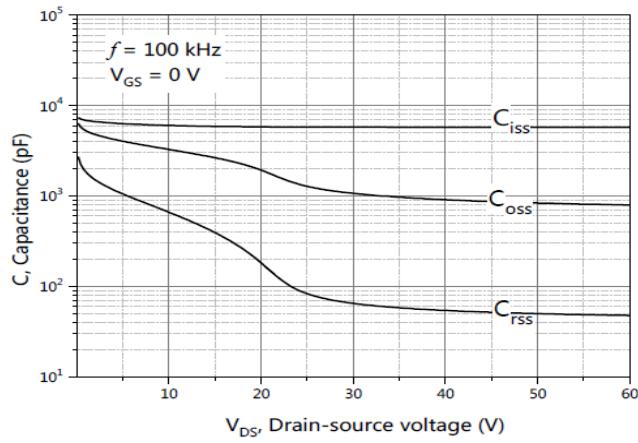


Figure3. Capacitance Characteristics

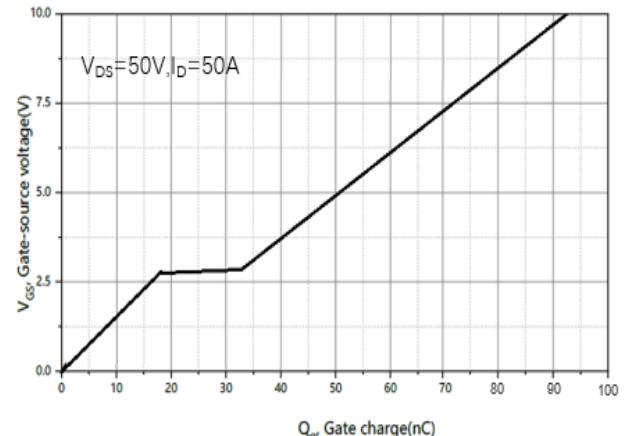


Figure4. Gate Charge

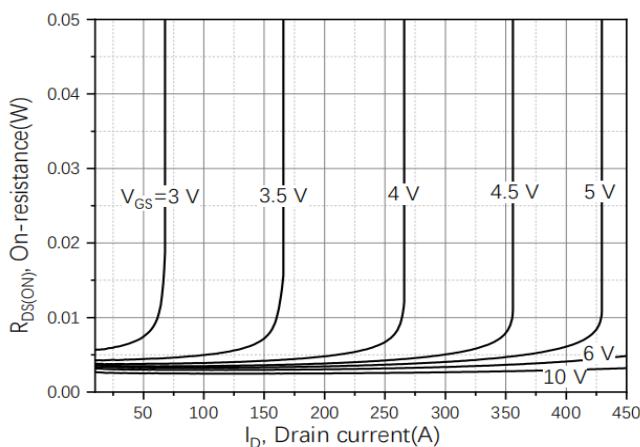


Figure5. Drain-Source on Resistance

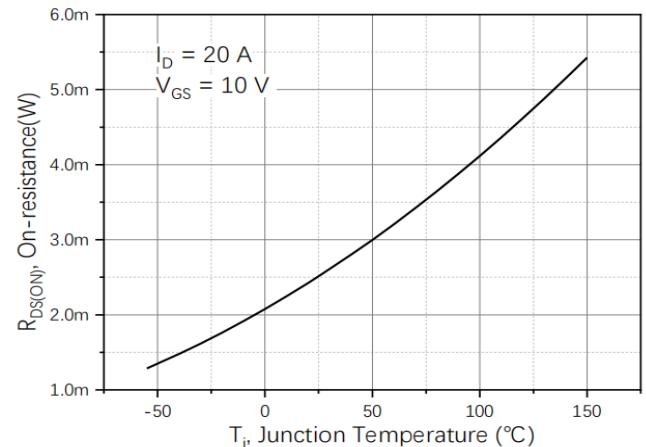


Figure6. Drain-Source on Resistance

## Typical Characteristics

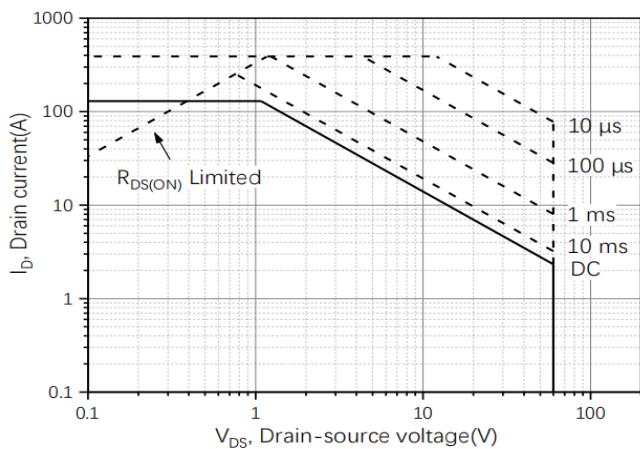


Figure 7. Safe Operation Area

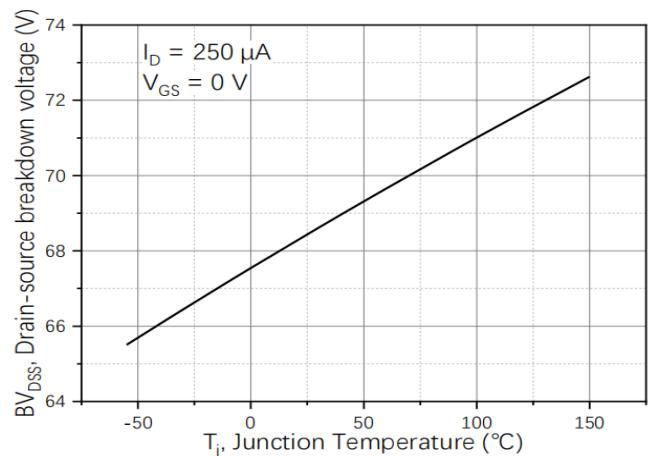


Figure 8. Drain-source breakdown voltage

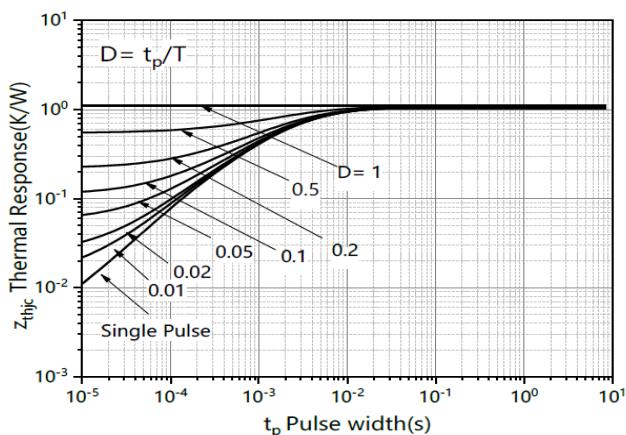


Figure 9. Transient thermal impedance

## Test circuits and waveforms

Figure A: Gate Charge Test Circuit &amp; Waveforms

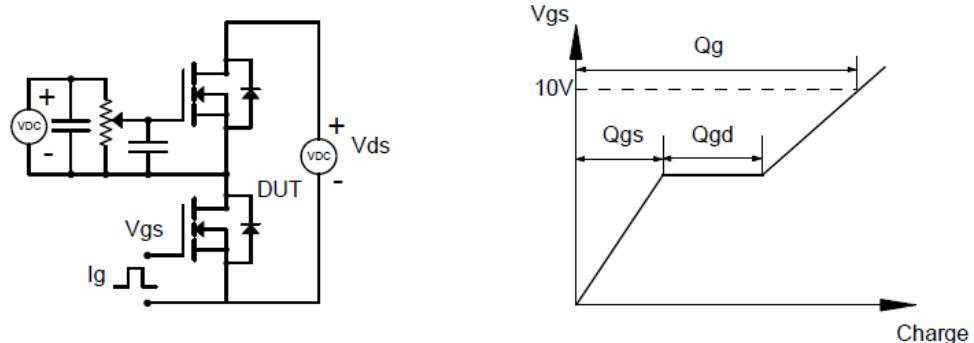


Figure B: Resistive Switching Test Circuit &amp; Waveforms

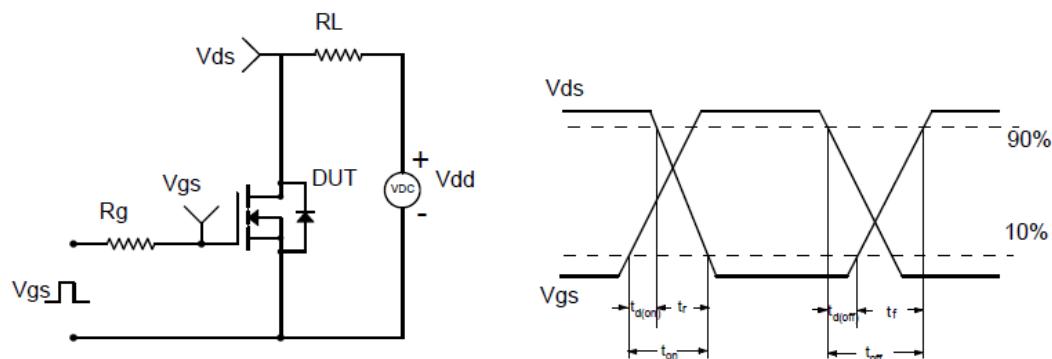


Figure C: Unclamped Inductive Switching (UIS) Test

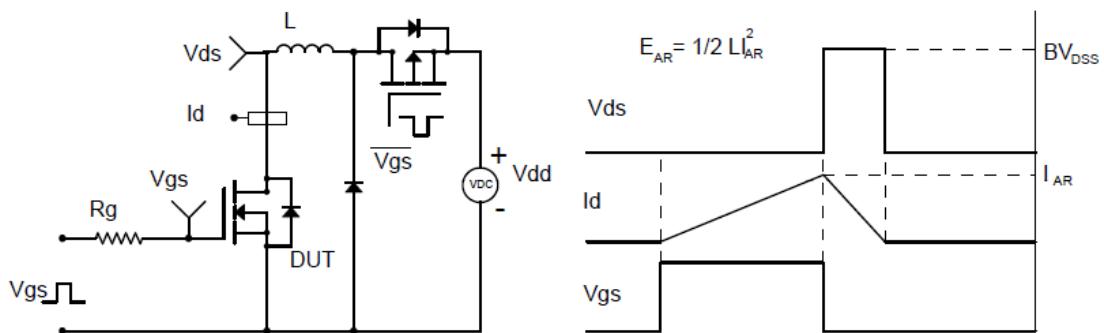
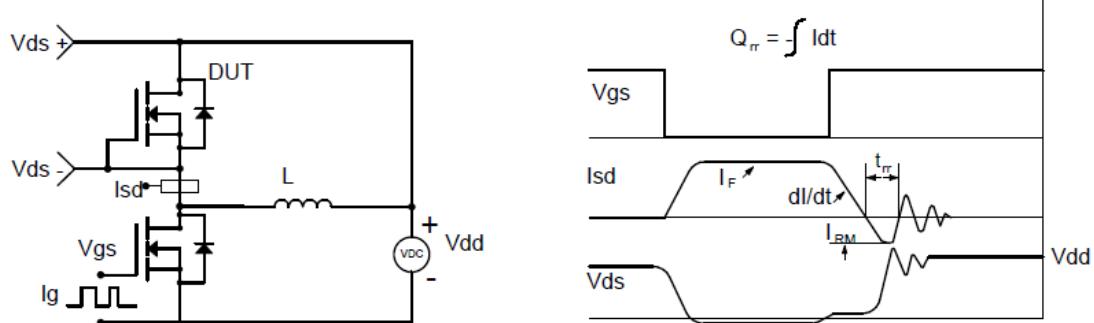
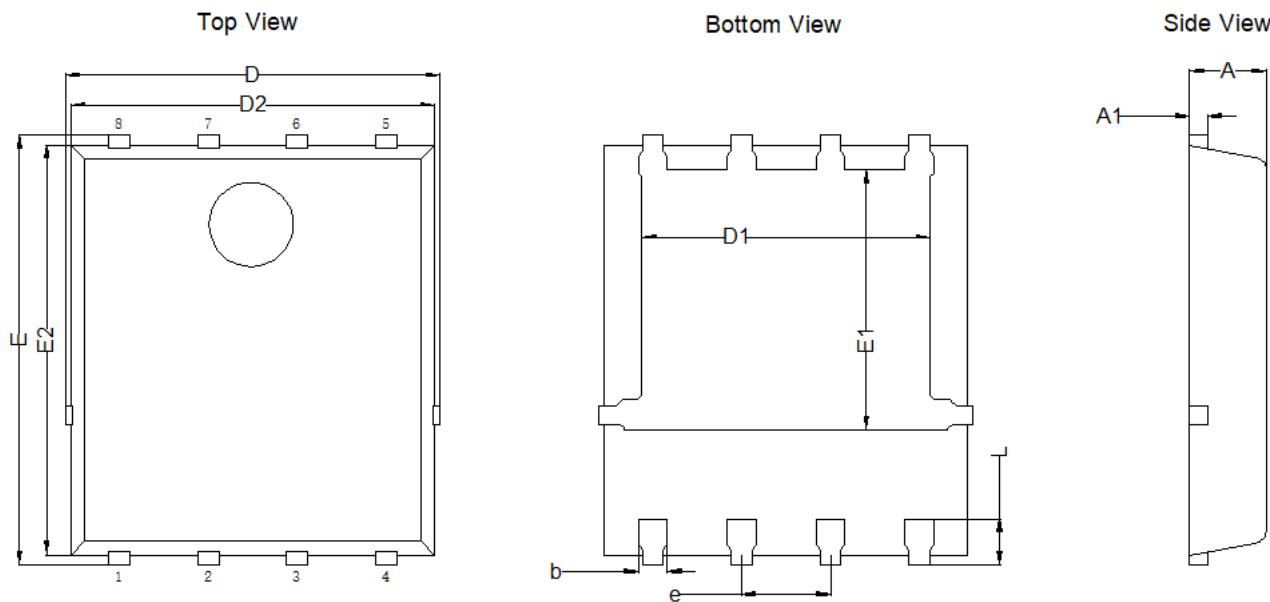


Figure D: Diode Recovery Test Circuit &amp; Waveforms



## PDFN5X6-8L Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	1.00	1.10	1.20
A1	0.254 BSC		
D	5.15	5.35	5.55
E	5.95	6.15	6.35
D1	3.92	4.12	4.32
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
e	1.27BSC		
b	0.31	0.41	0.51
L	0.56	0.66	0.76